NOTE:
CHECK "LaunchPad_Standard20.png" for board distances

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Sheet: 1
Design: 1
Engineer: Ian Cathey
Reviewer: e121903
Drawn by: Ian Cathey
File: TIDA-00250.SchDoc
Sheet Title: Piezoelectric Air Flow Sensor
Project Title: MSP430 LaunchPad Connector
Assembly Variant: 5/29/2014
Rev: B

Diameter of Hole: 0.053 mils (0.020 mils measured)
Center Hole to Center Hole: 0.198 mils (0.180 mils measured)

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